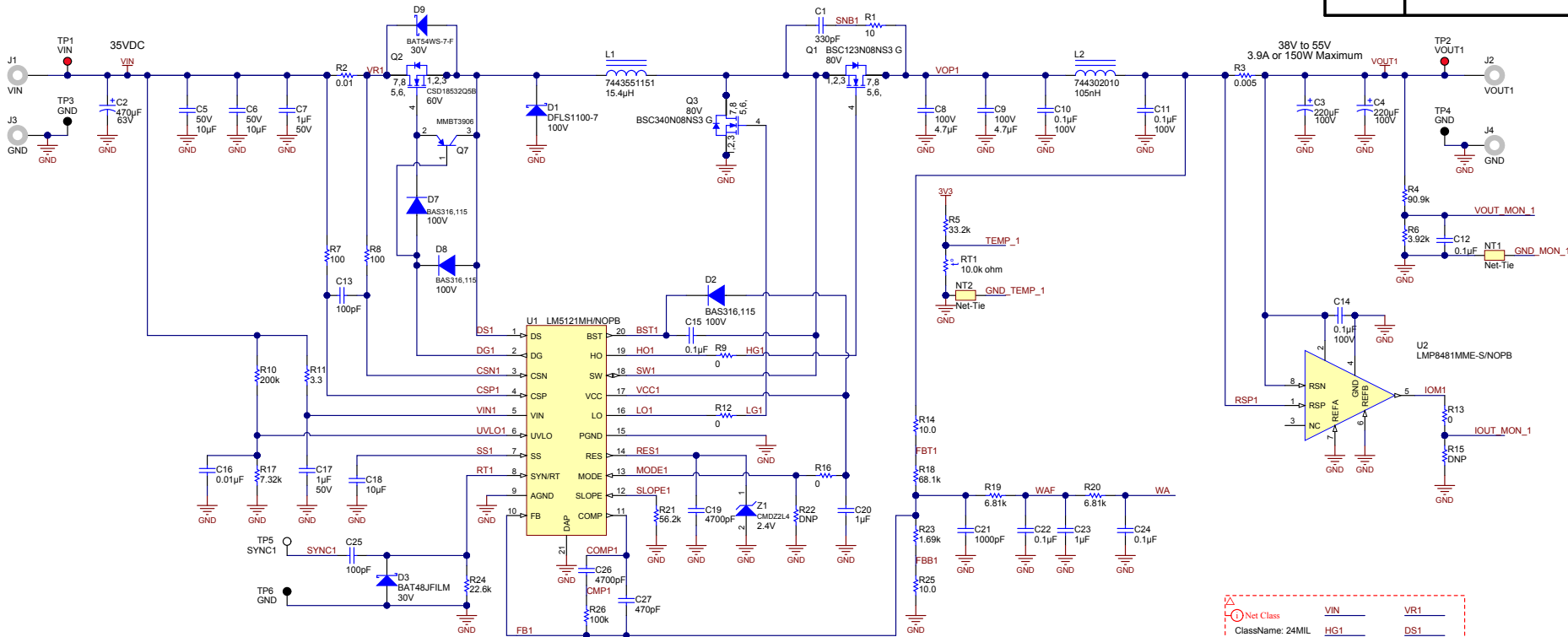


| Revision History |  |
|------------------|--|
| Revision         | Notes  |
| A                | Initial design   |
| B                | Circuit implementation to enhance short circuit protection .<br>Liam Murphy 11/26/13 |

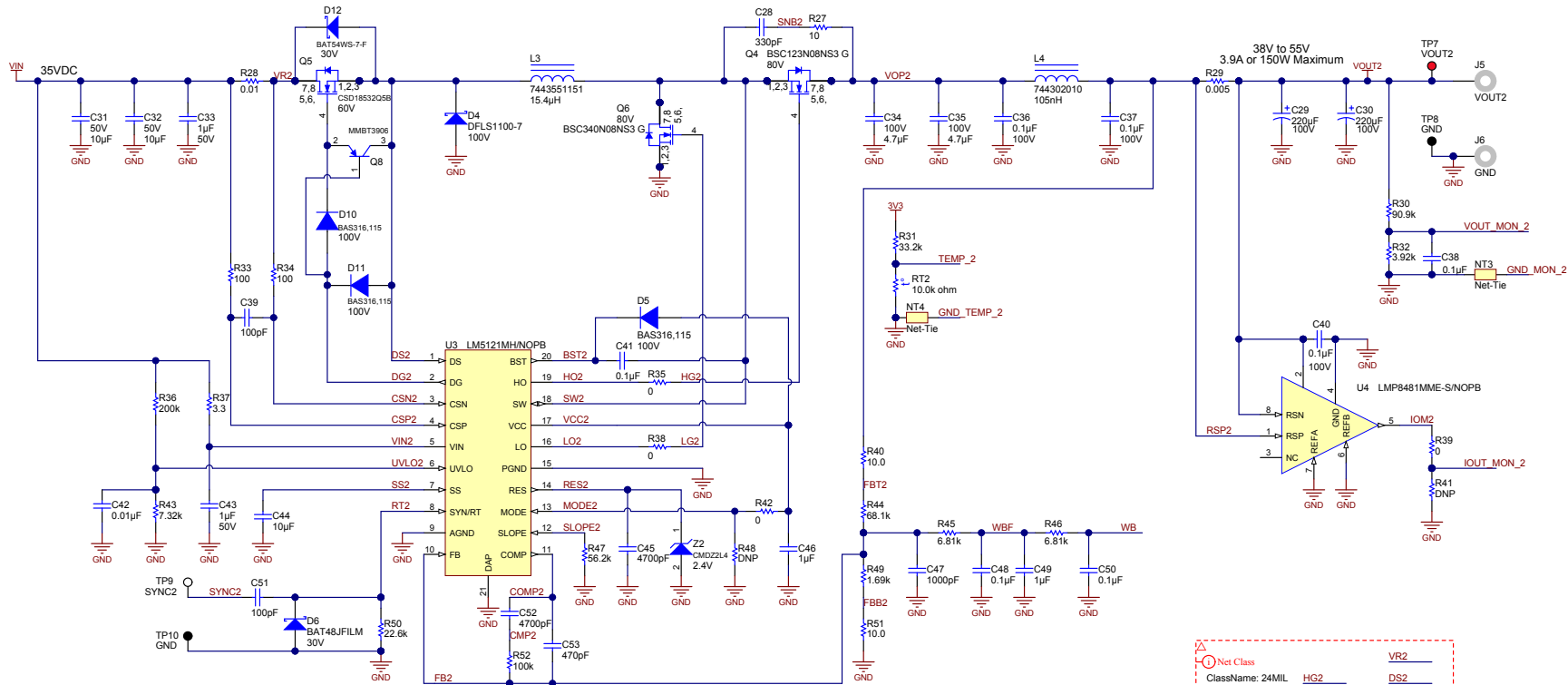


|                   |      |       |
|-------------------|------|-------|
| Net Class         | VIN  | VR1   |
| Class Name: 24MIL | HG1  | DS1   |
|                   | BST1 | SNB1  |
|                   | HO1  | DG1   |
|                   | SW1  | VOUT1 |
|                   | FBT1 | RSP1  |
|                   |      | VIN1  |

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|                                 |  |                                  |                       |
|---------------------------------|--|----------------------------------|-----------------------|
| Number: PMP9297                 | Rev: B   | Designed for: Public Release     | Mod. Date: 11/26/2013 |
| SVN Rev: Not in version control | Assembly Variant: Variant name not interpreted                             | Project Title: LMS121 Dual Boost | Sheet Title: Boost 1  |
| Drawn By: Robert Sheehan        | File: PMP9297_REV B_Sht1_SchDoc  |                                  | Sheet: 1 of 3         |
| Engineer: Robert Sheehan        | Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a> |                                  | Size: B               |

http://www.ti.com

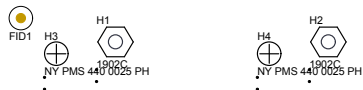
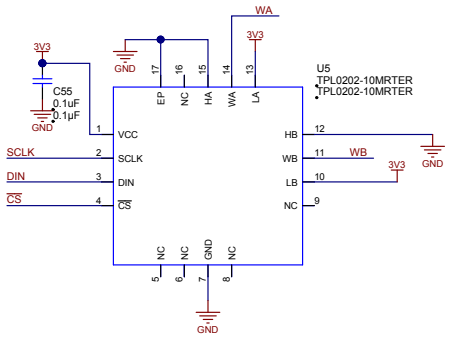
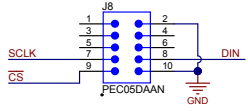
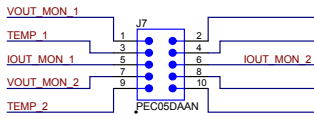
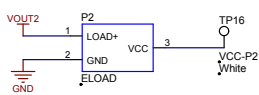
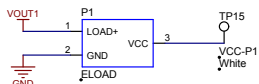
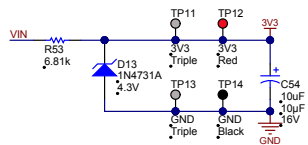


| Net Class        | VR2   |
|------------------|-------|
| ClassName: 24MIL | DS2   |
| BST2             | DG2   |
| HO2              | VOP2  |
| SW2              | VOUT2 |
| FBT2             | RSP2  |
|                  | VIN2  |

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|                                  |        |  |  |
|----------------------------------|--------|--|--|
| Designed for: Public Release     |        | Mod. Date: 11/26/2013                          |  |
| Project Title: LM5121 Dual Boost |        |  |  |
| Number: PMP9297                  | Rev: B | Sheet Title: Boost 2                           |  |
| SVN Rev: Not in version control  |        | Assembly Variant: Variant name not interpreted |  |
| Drawn By: Robert Sheehan         |        | File: PMP9297_REV_B_Sht_Sch.Doc                |  |
| Engineer: Robert Sheehan         |        | Contact: http://www.ti.com/support             |  |

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PCB Number: PMP9297  
PCB Rev: A

PCB LOGO  
Texas Instruments

LBL1  
PCB Label

Size: 0.65" x 0.20"  
ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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